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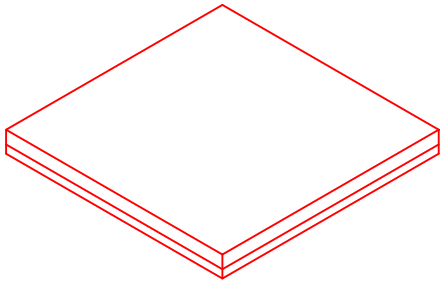
REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN# C02979	01/22/98	E.B.	HLE
01	CHANGED TO CURRENT FORMAT, DCN C03877	06/08/98	E.B.	HLE
02	UPDATED TOLERANCES PER DCN C04737	10/02/98	E.B.	HLE



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 56.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 10 X 10.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.50.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL	ANGULAR
X.X ±0.10	±1°
X.XX ±0.05	
X.XXX ±0.03	

MATERIAL: N/A

FINISH: N/A

DO NOT SCALE DRAWING

PROJECTION

APPROVALS		DATE
DRAWN	D. BIGGS	01/19/98
CHECKED	D. GASTELUM	01/19/98
ENG'R	T. PANCZAK	01/19/98
RELEASED	M. ANTONIO	01/22/98

ANAM Industrial Co., LTD.
Sungdong-Ku, Seoul, Korea

AMKOR Electronics, Inc.
Chandler, Arizona, USA

amkor anam

TITLE: PACKAGE OUTLINE – CABGA 56, 6.00mm X 6.00mm, 2 LAYER, 0.50mm PITCH, LAMINATE SUBSTRATE, AAP

SIZE	MFG NUMBER	DWG NUMBER	REV
B	N/A	73339	02

STEP DWG NUMBER/REV	CUST CODE	SCALE: 8:1	SHEET 1 OF 3
N/A	N/A		

ZF00094 REV E